

A Look Back over the Past Financial Year

> **October 2005** The move to the new corporate headquarters at Campeon, Neubiberg, begins. Here, about 6,000 employees from nine different sites in and around Munich will now have their new workplaces. But the site also offers employees a range of amenities including shopping facilities, a children's day-care center, a fitness center and a bank branch office.

Infineon announces its new high-voltage power transistors of the CoolMOS® CP family, which have the lowest on-state resistance in the industry. These transistors are used to provide energy for telecommunications devices, notebooks and consumer applications. They are more efficient and enable compact power packs because they have little heat dissipation and switching loss.

> **November 2005** On November 17 – one day before official publication of the annual results and the accompanying press conference – the carve-out of the Memory Products division is announced. The date foreseen for the carve-out is July 2006.

> **December 2005** On December 12, ATI technologies selected Infineon's 512 Mbit GDDR3 (Graphics Double Data Rate 3) memory, for use with its Mobility Radeon X1600, ATI's latest notebook graphics processor.

> **January 2006** Infineon supplies the first samples of its dual-mode radio-frequency CMOS transceiver, SMARTi® 3GE, for use in cell phones and other mobile devices using WCDMA and EDGE transmission standards. This is the world's first one-chip solution for WCDMA (6-band) and EDGE (4-band).

On January 18, Infineon opens its newest development center in Bucharest, Romania. The center's approximately 60 developers will work primarily on special power semi-conductors which will increasingly be used in automotive and industrial applications as well as in security controllers on chip cards.

> **February 2006** The move to Campeon is completed in February. Step by step, thousands of the most modern workplaces are completed. There are no longer any telephone cables. The entire voice communication traffic is channeled through the computer network using Internet telephony.



On February 16, the Annual General Meeting is held at ICM – International Congress Center in Munich, Germany. This, the sixth AGM since the firm's IPO, was attended by about 3,500 people. More than 54 percent of the company's share capital were represented.



> **March 2006** Our first front-end facility in Asia, at Kulim in Malaysia, is "Ready for Equipment", reaching the most important stage of construction on schedule. The highly sensitive production equipment can now be installed.



> **March 2006**

Deutsche Telekom is the first network operator in the world to install a VDSL2 network with speeds of up to 50 megabits per second. The network is launched in 10 German cities and uses Infineon's VINAX™ chipsets.

Volume production begins of the world's first one-chip mobile telephone compliant with the GSM/GPRS wireless standard. This is a milestone in the history of mobile telephony. Based on the central component, E-GOLDradio™, a Chinese customer produces entry-level telephones for the Asian market as well as for Africa and South America.

On March 31, the new name of the Memory Products spin-off is announced: Qimonda. Chosen because of its universal character, the name is expected to have worldwide appeal. The initial syllable "Qi" stands for "living and flowing energy". In Western cultures the name is to be interpreted as the "key to the world" (combining "key" with the Latin "mundus").



> **April 2006**

Infineon is the world's first semiconductor manufacturer to begin with volume production of embedded Flash microcontrollers in 130-nanometer technology for automotive uses. The two 32-bit microcontrollers TC 1766 and TC 1796 were developed for engine and transmission control in automobiles and motorcycles.

> **May 2006**

Qimonda starts operative business life as an independent company on May 1. Munich is chosen as the headquarters of the company and its legal place of business. Its stock exchange listing will be on the New York Stock Exchange.

> **June 2006**

On June 5, the most highly integrated one-chip solution for ASDL2+ is presented to the industrial world. This chip, named Danube™, enables Voice-over-IP, video conferences and Internet television with only a few components.

> **July 2006**

LG Electronics becomes a customer for Infineon's EDGE multimedia platform MP-E. The platform incorporates the baseband chip S-GOLD®2, the radio-frequency transceiver SMARTi® PM, the power-management chip SM-Power, the Bluetooth chip BlueMoon® UniCellular and the accompanying software.



> **August 2006**

On August 9, Qimonda begins its listing on the New York Stock Exchange under the ticker symbol "QI". The initial share price is fixed at U.S.\$13. About 13.6 million shares were traded on the first day and the share price closed at U.S.\$13.54. On November 30, 2006, the share price stood at U.S.\$18.85.



On August 26, we were awarded the contract to supply high-security chips for the world's largest national passport project, the U.S. electronic passport. The U.S. government intends to start issuing the forgery-proof passports to citizens by the end of the year and to issue some 15 million of them within the first year.

> **September 2006**

Official opening of our front-end production facility in Asia is attended by the Malaysian Minister of International Trade and Industry. The celebrations held on September 12, mark the formal opening of the facility in Kulim.

